

CLAIMS

What is claimed is:

- 1 1. A heat sink assembly that is coupled to an electronic device and a
2 motherboard, the heat sink assembly comprising:
3 a heat sink that includes an opening;
4 a pin extending through the motherboard and the opening in the heat sink to
5 couple the heat sink to the electronic device and the motherboard; and
6 a member within the opening in the heat sink, the member being between the
7 heat sink and the pin.
- 1 2. The heat sink assembly of claim 1, wherein the member is a bushing that is
2 pressed into the opening in the heat sink.
- 1 3. The heat sink assembly of claim 2, wherein the pin is pressed through an
2 opening in the bushing.
- 1 4. The heat sink assembly of claim 1, wherein the member is plastic.
- 1 5. The heat sink assembly of claim 1, wherein the member has a lower thermal
2 conductivity than the pin and the heat sink.
- 1 6. The heat sink assembly of claim 1, wherein the member has a lower
2 Modulus of Elasticity than the pin and the heat sink.
- 1 7. The heat sink assembly of claim 1, wherein the member is partially within
2 the opening in the heat sink.

1 8. The heat sink assembly of claim 1, wherein the pin includes a head that is
2 larger than the opening in the heat sink.

1 9. The heat sink assembly of claim 8, wherein the head of the pin engages the
2 heat sink.

1 10. The heat sink assembly of claim 1, wherein the pin includes a body that is
2 cylindrical, and the opening in the heat sink is cylindrical.

1 11. A method comprising:
2 thermally coupling a heat sink to an electronic device;
3 securing the heat sink to a motherboard using a pin that extends through an
4 opening in the heat sink; and
5 positioning a member between the pin and the heat sink within the opening
6 in the heat sink.

1 12. The method of claim 11, further comprising wave soldering the pin to the
2 motherboard.

1 13. The method of claim 11, wherein positioning a member between the pin and
2 the heat sink within the opening in the heat sink includes pressing a bushing into the
3 opening in the heat sink.

1 14. The method of claim 13, wherein positioning a member between the pin and
2 the heat sink within the opening in the heat sink includes pressing the pin through an
3 opening in the bushing.

1 15. The method of claim 11, wherein positioning a member between the pin and
2 the heat sink within the opening in the heat sink includes positioning the entire
3 member within the opening in the heat sink.

1 16. The method of claim 11, wherein positioning a member between the pin and
2 the heat sink within the opening in the heat sink includes placing a member that is
3 more elastic than the pin and the heat sink between the pin and the heat sink to
4 alleviate stress between the pin and heat sink.

1 17. A computer system comprising:
2 a motherboard;
3 an electronic device coupled to the motherboard;
4 a heat sink that includes an opening;
5 a pin extending through the motherboard and the opening in the heat sink to
6 couple the heat sink to the electronic device and the motherboard; and
7 a member within the opening in the heat sink, the member being between the
8 heat sink and the pin.

1 18. The computer system of claim 17, wherein the member has a lower thermal
2 conductivity than the pin.

1 19. The computer system of claim 17, wherein the member has a lower Modulus
2 of Elasticity than the pin.

1 20. The computer system of claim 17, further comprising a chassis, the
2 motherboard being attached to the chassis.